kerno

OKAM K01-2210

Rack Server - 2U DP 24-Bay NVMe/SATA/SAS

Key Features

- Dual 5th/4th Gen Intel® Xeon® Scalable Processors
- Dual Intel® Xeon® CPU Max Series
- 8-Channel DDR5 RDIMM, 32 x DIMMs
- Dual ROM Architecture supported
- 2 x 1Gb/s LAN ports via Intel® I350-AM2
- 8 x 2.5" Gen4 NVMe hot-swappable bays
- 16 x 2.5" SATA/SAS hot-swappable bays
- 4 x FHHL PCIe Gen5 x16 slots
- 4 x LP PCIe Gen5 x8 slots
- 2 x OCP 3.0 Gen5 x16 slots
- 1+1 2000W 80 PLUS Platinum redundant power supplies

Applications

Networking, Hybrid/Private Cloud Server

Specification

Dimensions	2U (W438 x H87.5 x D815 mm)
CPU	5th Generation Intel® Xeon® Scalable Processors 4th Generation Intel® Xeon® Scalable Processors Intel® Xeon® CPU Max Series Dual processor, TDP up to 350W
OS Compatibility	Visit our website for the list of compatible OS
Socket	2 x LGA 4677 (Socket E)
Chipset	Intel® C741 Chipset
Memory	32 x DIMM slots, 8-Channel DDR5 memory RDIMM up to 96GB supported 3DS RDIMM up to 256GB supported Memory speed: Up to 5600 MT/s (1DPC), 4400 MT/s (2DPC
LAN	2 x 1Gb/s LAN ports (1 x Intel® I350-AM2) - Supported NCSI 1 x 10/100/1000 management LAN
Video	ASPEED® AST2600 Integrated 2D Graphic Adapter
Storage	Front side: 8 x 2.5" Gen4 NVMe hot-swappable bays 16 x 2.5" SATA/SAS hot-swappable bays *SAS card is required for SAS devices support
RAID	Intel® SATA RAID 0/1/10/5

TPM	1 x TPM header with SPI interface - Optional TPM2.0
Expansion Slots	4 x FHHL PCIe Gen5 x16 slots 4 x LP PCIe Gen5 x8 slots 2 x OCP 3.0 Gen5 x16 slots - Supports NCSI function
I/O Ports	Front: 2 x USB 3.2 Gen1 Rear: 2 x USB 3.2 Gen1, 1 x Mini-DP, 2 x RJ45, 1 x MLAN Internal: 1 x TPM header, 1 x VROC connector
Backplane Board	Speed and bandwidth: PCIe Gen4 x4 or SATA 6Gb/s or SAS 12Gb/s
Power Supply	1+1 2000W 80 PLUS Platinum redundant power supplies AC Input: 100-240V
System Management	ASPEED® AST2600 management controller KERNO Management Console (AMI MegaRAC SP-X)
System Fans	4 x 80x80x38mm (18,300rpm
Operating Properties	Operating temperature: 10°C to 35°C Operating humidity: 8-80% (non-condensing) Non-operating temperature: -40°C to 60°C Non-operating humidity: 20%-95% (non-condensing)
Packaging Content	1 x 2U Chassis, 2 x CPU heatsinks, 6 x Carrier clips, 1 x Mini-DP to D-Sub cable, 1 x -Section Rail kit Packaging Dimensions: 1077 x 679 x 300 mm

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